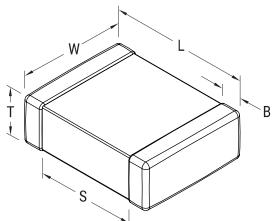


C0805X561M2TACTU

Aliases (C0805X561M2TAC7800) SMD Comm X8G HT150C Flex, Ceramic, 560 pF, 20%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0805, 0.6 mm



General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	11 mg
Shelf Life	78 Weeks
MSI	1

0.1% 1 MHz 1.0Vrms

Time is 1000 Hours

100 GOhms

0% Loss/Decade Hour: Referee

Dimensions		Specifications	
Chip Size	0805	Capacitance	560 pF
L	2mm +/-0.3mm	Measurement Condition	1 MHz 1.0Vrms
W	1.25mm +/-0.3mm	Tolerance	20%
т	0.78mm +/-0.20mm	Voltage DC	200 VDC
S	0.6mm MIN	Dielectric Withstanding Voltage	500 VDC
В	0.5mm +/-0.25mm	Temperature Range	-55/+150°C
		Temp. Coefficient	X8G
Packaging Specifications		Capacitance Change with	30 ppm/C, 1MegaHz 1.0Vrms
Packaging	T&R, 180mm, Plastic Tape	Reference to +25°C and 0 VDC Applied (TCC)	
Packaging Quantity	4000		0.1% 1 MI I= 1.0) /mm =

Dissipation Factor

Insulation Resistance

Aging Rate

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Click here for the 3D model.		Typical Component W
		Shelf Life
		MSL
		Specifications
	0805	Specifications Capacitance
	0805 2mm +/-0.3mm	